

# CUSTOMER APPROVAL SHEET

**Company Name**

**MODEL** X120BLN02

**CUSTOMER** Title :

**APPROVED** Name :

- APPROVAL FOR SPECIFICATIONS ONLY (Spec. Ver.\_\_\_\_)
- APPROVAL FOR SPECIFICATIONS AND ES SAMPLE (Spec. Ver.\_\_\_\_)
- APPROVAL FOR SPECIFICATIONS AND CS SAMPLE (Spec. Ver.\_\_\_\_)
- CUSTOMER REMARK :



Version 1.2

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# Product Specification

1.20" Color AMOLED

**MODEL NAME: X120BLN02**

MP product P/N:

< ◆ > Preliminary Specification

< > Final Specification

Note: The content of this specification is subject to change.

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**Record of Revision**

Version	Revise Date	Page	Content
0.0	2016-11-1	1~23	First Draft
0.1	2016-11-8	7	Update sleep in mode data
1.0	2016-11-18	4	Update interface information
		4	Update pin assignment information
		7	Update Display Current Consumption information
		11	Update SPI Interface Characteristics
		15	Update Power Structure & Power on/off Sequence
		17	Update Boost Mode information
		20	Update ESD criteria
		23	Update 2D drawing
1.1	2017-1-17	4	Update outline Dimension
1.2	2017-3-7	23	Update packing information

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## A. General Specification

### 1. Physical Specifications

NO	Item	unit	Specification	Remark
1	Screen Size	inch	1.20"	
2	Display Resolution	--	390 x 390	
3	Outline Dimension	mm	33.22 (H) × 34.72 (V) × 0.66(T)	
4	Active Area	mm	30.42 (H) × 30.42 (V)	
5	Color Configuration	--	Hyper R.G.B	
6	Color Depth	--	16.7M	
7	Display Mode	--	AMOLED	
8	Interface	--	MIPI (command mode) + SPI	
9	Display IC		AUO W022 ASIC	

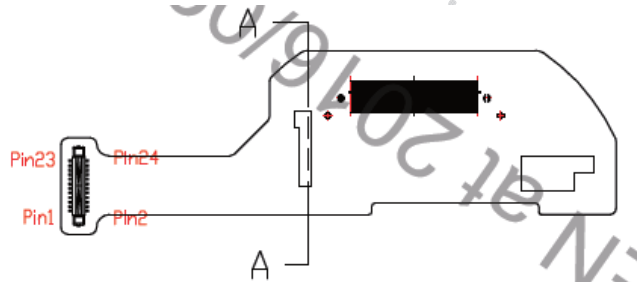
### 2. Pin Assignment

Main FPC Pin assignment — AMOLED Panel Input/Output Signal Interface

FPCA recommended connector: BM28B0.6-24DP/2-0.35V(51)

Main board recommended connector: BM28B0.6-24DS/2-0.35V(51)

Pin location



Pin assignment

PIN NO.	SYMBOL	DESCRIPTION	REMARK
1	XRES	Device reset signal(0:enable;1:Disable)	
2	VCI_EN	Enable signal for PWR IC control	
3	NC	Floating	
4	GND	Ground	
5	TE	Vsync (vertical sync) signal output from panel to avoid tearing effect	

6	DSI_D0N	MIPI negative data signal	
7	CSX	SPI Enable Signal	
8	DSI_D0P	MIPI positive data signal	
9	SCL	SPI Clock Signal	
10	GND	Ground	
11	DCX	SPI CMD/Data selection signal	
12	DSI_CLKN	MIPI negative clock signal	
13	SDI	SPI data signal	
14	DSI_CLKP	MIPI positive clock signal	
15	SDO	SPI output signal	
16	GND	Ground	
17	NC	Floating	
18	VDDI	Power supply for interface system except MIPI interface	
19	VBAT	Driver analog power supply (Power IC need to follow AUO's suggestion)	
20	VDDI	Power supply for interface system except MIPI interface	
21	VBAT	Driver analog power supply (Power IC need to follow AUO's suggestion)	
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23	VBAT	Driver analog power supply (Power IC need to follow AUO's suggestion)	
24	VBAT	Driver analog power supply (Power IC need to follow AUO's suggestion)	

### 3. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit	Remark
Digital Power Supply	VDDIO	-0.3	5.5	V	
Analog Power Supply	VBAT	-0.3	5.5	V	
ELVDD power Supply	ELVDD	-	5.0	V	
ELVSS power Supply	ELVSS	-5.0	-	V	

Note : If the module exceeds the absolute maximum ratings, it may be damaged permanently. Also, if the module operates with the absolute maximum ratings for a long time, the reliability may drop.

## B. DC Characteristics

### 1. Typical Operating Conditions

Item	Symbol	Min.	Typ.	Max.	Unit	Remark	
Digital Power Supply	VDDIO	1.65	1.8	1.95	V	Note1	
Analog power Voltage	VBAT	3.27	3.3	3.33	V	Note1	
ELVDD power Supply	ELVDD	3.27	3.3	3.33	V	Note1	
ELVSS power Supply	ELVSS	-3.33	-3.3	-3.27	V	Note1	
Input Signal Voltage	H Level	VIH	0.8* VDDIO	-	VDDIO	V	Note1
	L Level	VIL	0	-	0.2* VDDIO	V	
Output Signal Voltage	H Level	VOH	0.8* VDDIO	-	VDDIO	V	Note1
	L Level	VOL	0	-	0.2* VDDIO	V	Note1

Note 1: The operation is guaranteed under the recommended operating conditions only. The operation is not guaranteed if a quick voltage change occurs during the operation. To prevent the noise, a bypass capacitor must be inserted into the line closed to the power pin.

## 2. Display Current Consumption

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Remark	
<b>Panel Power</b>	P <sub>OLED</sub>	ELVDD:3.3V	--	--	128.7	mW	Note1	
	I <sub>OLED</sub>	ELVSS:-3.3V	--	--	19.5	mA	Note1	
<b>IC</b>	<b>Normal</b>	P <sub>VCI</sub>	VCI : 3.3V	--	5.3	--	mW	Note2
		I <sub>VCI</sub>		--	1.6	--	mA	Note2
		P <sub>VDDIO</sub>	VDDIO :1.8V	--	3.5	--	mW	Note2
		I <sub>VDDIO</sub>		--	1.9	--	mA	Note2
	<b>Idle</b>	P <sub>VCI</sub>	VCI : 3.3V	--	4.5	--	mW	Note3/4
		I <sub>VCI</sub>		--	1.4	--	mA	Note3/4
		P <sub>VDDIO</sub>	VDDIO :1.8V	--	2.4	--	mW	Note3/4
		I <sub>VDDIO</sub>		--	1.3	--	mA	Note3/4
	<b>Sleep</b>	P <sub>VCI</sub>	VCI : 3.3V	--	0.075<	--	mW	
		I <sub>VCI</sub>		--	22.6<	--	uA	
		P <sub>VDDIO</sub>	VDDIO :1.8V	--	0.1<	--	mW	
		I <sub>VDDIO</sub>		--	55<	--	uA	

Note 1: Based on L255 (350nits) full white pattern

Note 2: Based on black pattern / command mode.

Note 3: Based on black pattern / MIPI - command mode or SPI interface.

Note 4: IVCI < 8mA at Idle mode.



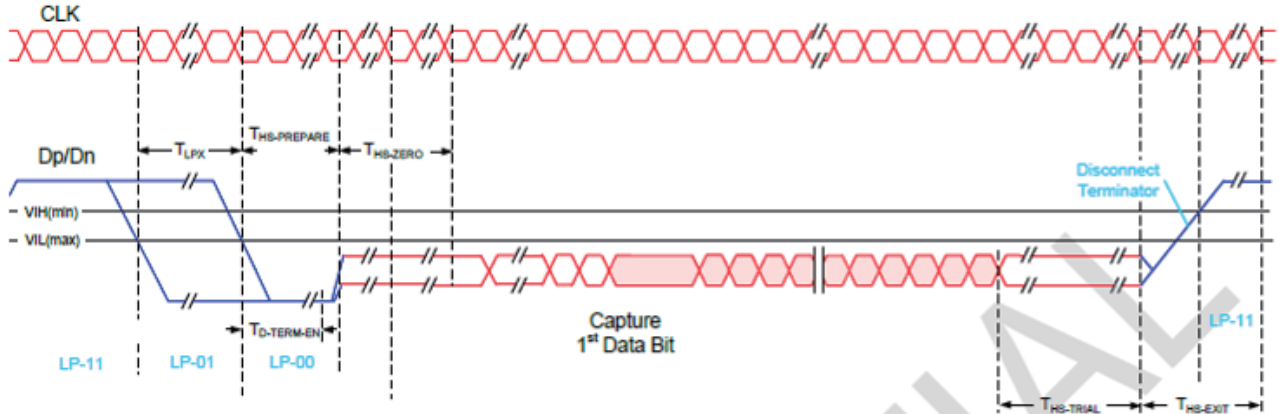
## C. AC Characteristics

### 1. MIPI / SPI Interface Characteristics

#### MIPI Interface Characteristics

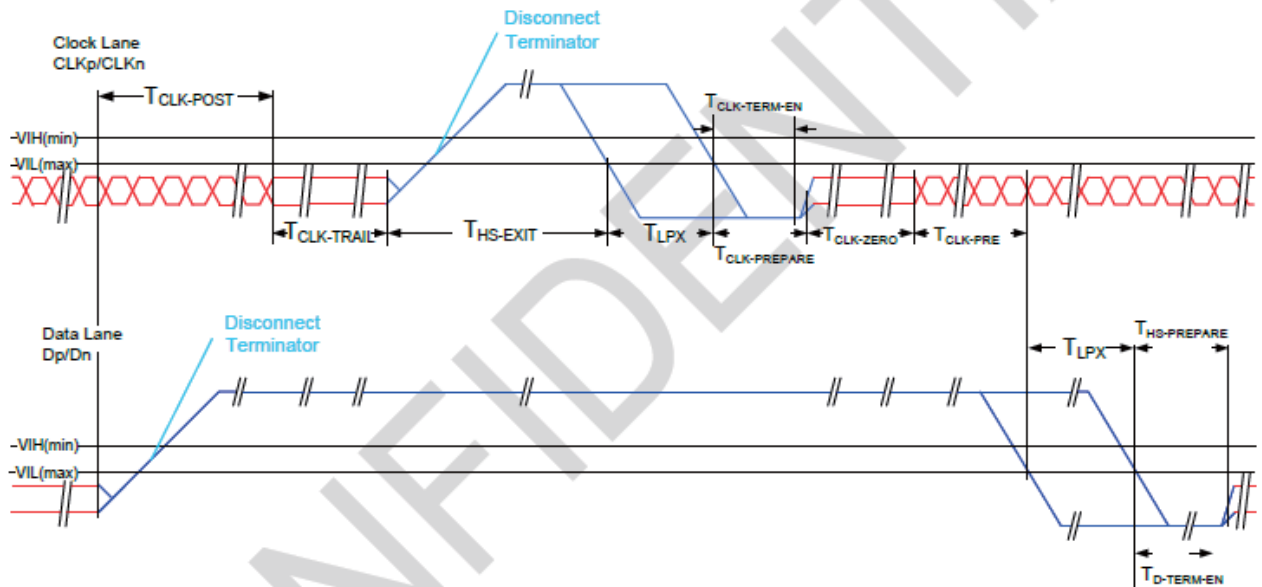
##### HS Data Transmission Burst

##### HS Data Transmission Burst



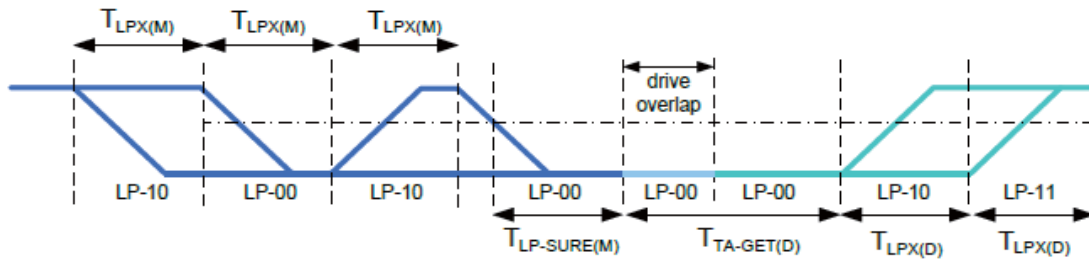
##### HS clock transmission

##### HS clock transmission



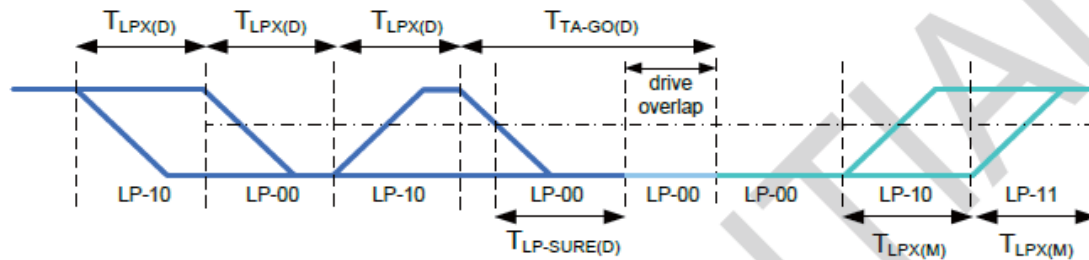
## Turnaround Procedure

### Turnaround Procedure



Bus turnaround (BAT) from MPU to display module timing

### Bus turnaround (BAT) from MPU to display module timing



Bus turnaround (BAT) from display module to MPU timing

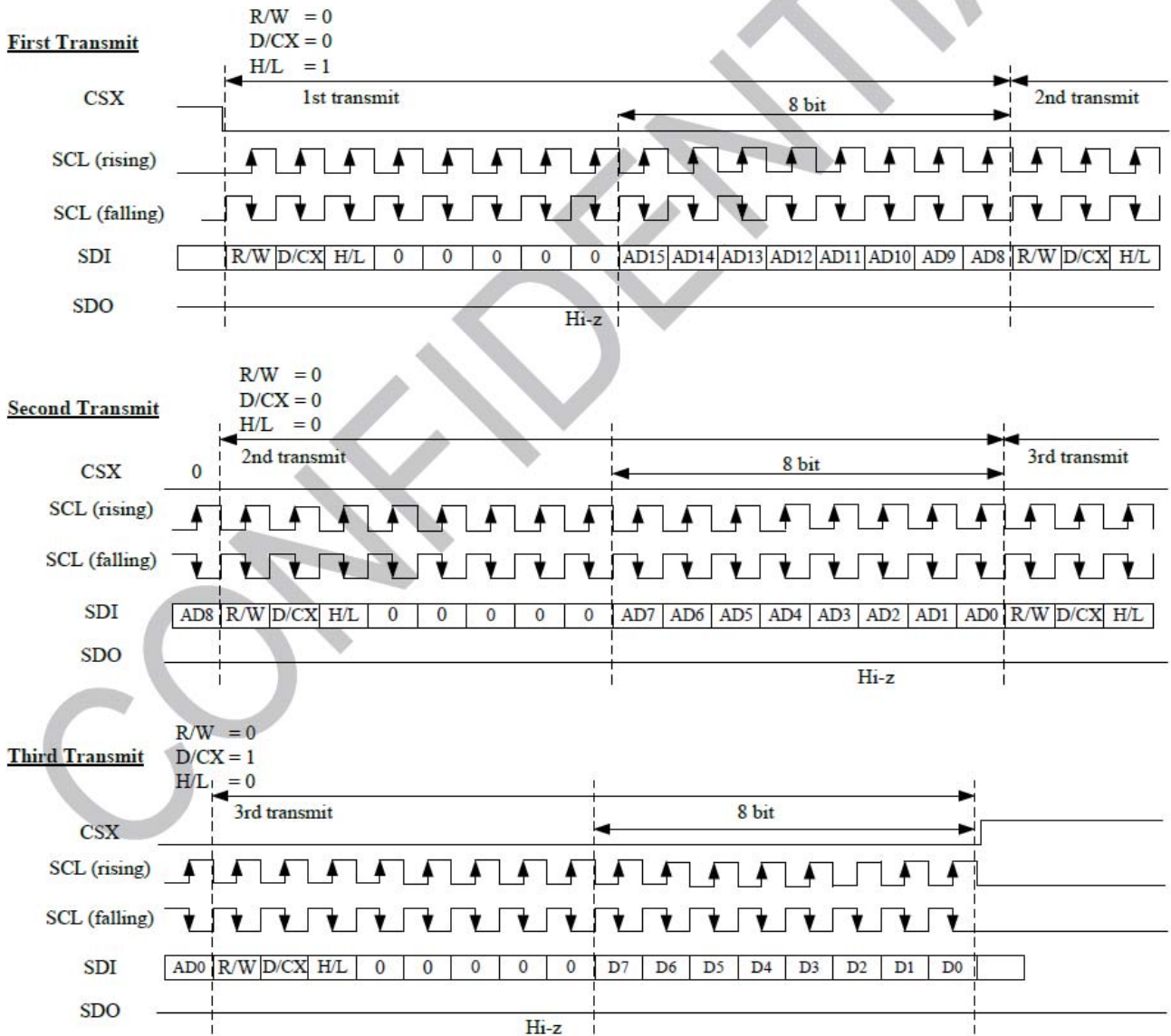
## Timing Parameters

Symbol	Description	Min	Typ	Max	Unit
$T_{CLK-POST}$	Time that the transmitter continues to send HS clock after the last associated Data Lane has transitioned to LP Mode. Interval is defined as the period from the end of $T_{HS-TRAIL}$ to the beginning of $T_{CLK-TRAIL}$ .	$60ns + 52 \cdot UI$			ns
$T_{CLK-TRAIL}$	Time that the transmitter drives the HS-0 state after the last payload clock bit of a HS transmission burst.	60			ns
$T_{HS-EXIT}$	Time that the transmitter drives LP-11 following a HS burst.	300			ns
$T_{CLK-TERM-EN}$	Time for the Clock Lane receiver to enable the HS line termination, starting from the time point when Dn crosses $V_{IL,MAX}$ .	Time for Dn to reach $V_{TERM-EN}$		38	ns
$T_{CLK-PREPARE}$	Time that the transmitter drives the Clock Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission.	38		95	ns
$T_{CLK-PRE}$	Time that the HS clock shall be driven by the transmitter prior to any associated Data	8			UI

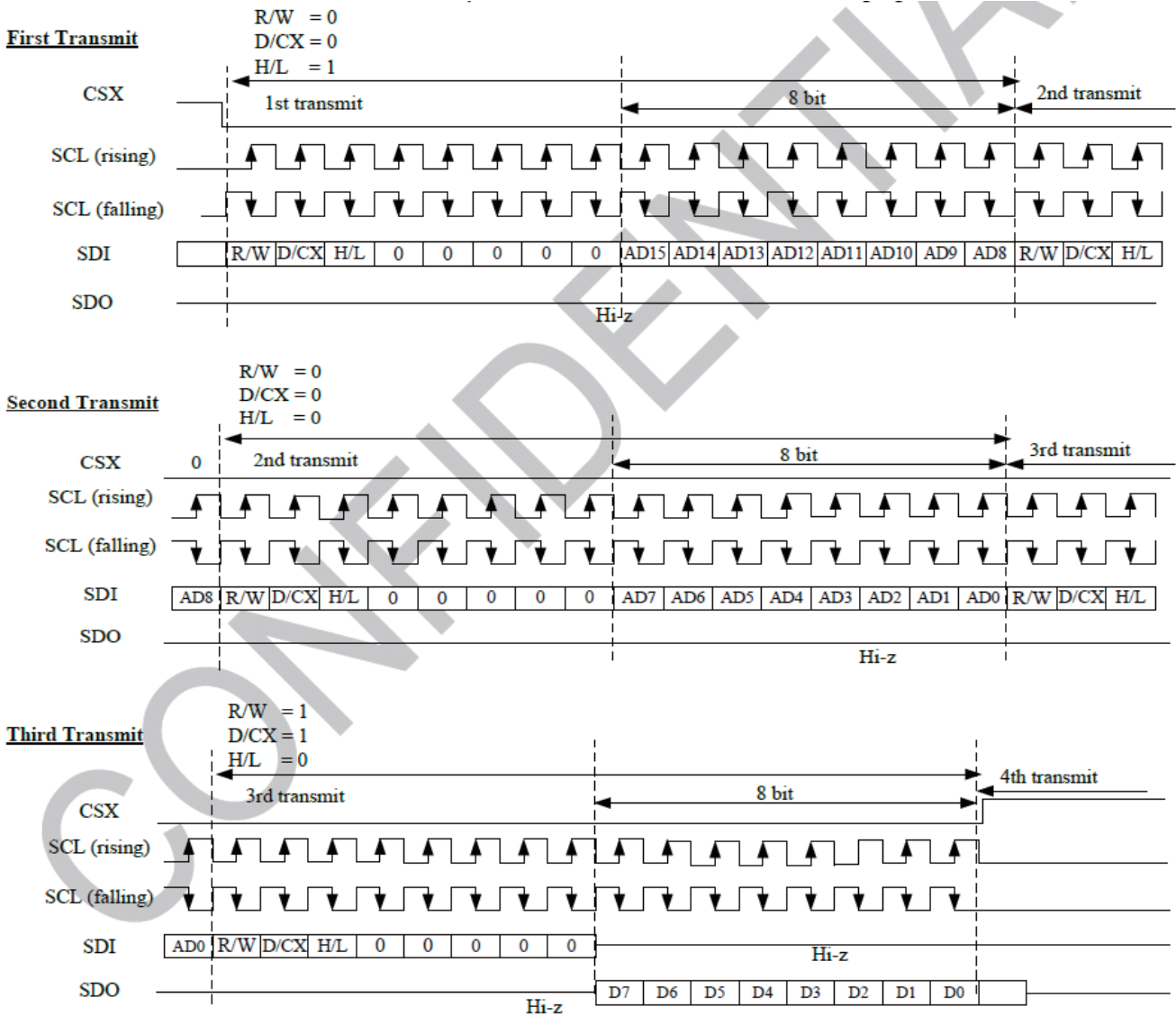
	Lane beginning the transition from LP to HS mode.				
$T_{\text{CLK-PREPARE}} + T_{\text{CLK-ZERO}}$	$T_{\text{CLK-PREPARE}}$ + time that the transmitter drives the HS-0 state prior to starting the Clock.	300			ns
$T_{\text{D-TERM-EN}}$	Time for the Data Lane receiver to enable the HS line termination, starting from the time point when Dn crosses $V_{\text{IL,MAX}}$ .	Time for Dn to Reach $V_{\text{TERM-EN}}$		35 ns + $4*UI$	
$T_{\text{HS-PREPARE}}$	Time that the transmitter drives the Data Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission	$40\text{ns} + 4*UI$		$85 \text{ ns} + 6*UI$	ns
$T_{\text{HS-PREPARE}} + T_{\text{HS-ZERO}}$	$T_{\text{HS-PREPARE}}$ + time that the transmitter drives the HS-0 state prior to transmitting the Sync sequence.	$145\text{ns} + 10*UI$			ns
$T_{\text{HS-TRAIL}}$	Time that the transmitter drives the flipped differential state after last payload data bit of a HS transmission burst	$60\text{ns} + 4*UI$			ns
$T_{\text{LPX(M)}}$	Transmitted length of any Low-Power state period of MCU to display module	50		150	ns
$T_{\text{TA-SURE(M)}}$	Time that the display module waits after the LP-10 state before transmitting the Bridge state (LP-00) during a Link Turnaround.	$T_{\text{LPX(M)}}$		$2*T_{\text{LPX(M)}}$	ns
$T_{\text{LPX(D)}}$	Transmitted length of any Low-Power state period of display module to MCU	50		150	ns
$T_{\text{TA-GET(D)}}$	Time that the display module drives the Bridge state (LP-00) after accepting control during a Link Turnaround.		$5*T_{\text{LPX(D)}}$		ns
$T_{\text{TA-GO(D)}}$	Time that the display module drives the Bridge state (LP-00) before releasing control during a Link Turnaround.		$4*T_{\text{LPX(D)}}$		ns
$T_{\text{TA-SURE(D)}}$	Time that the MPU waits after the LP-10 state before transmitting the Bridge state (LP-00) during a Link Turnaround.	$T_{\text{LPX(D)}}$		$2*T_{\text{LPX(D)}}$	ns

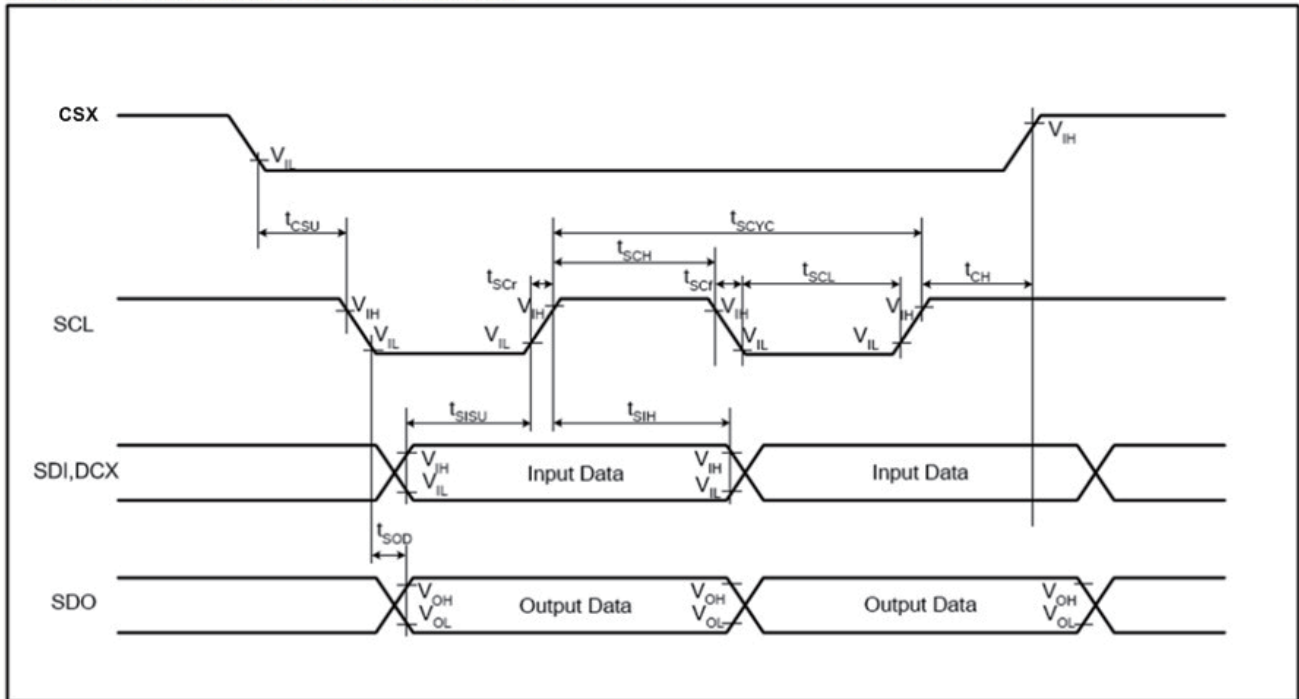
SPI Interface Characteristics

Write Cycle in SPI I/F



**Read Cycle in SPI I/F**



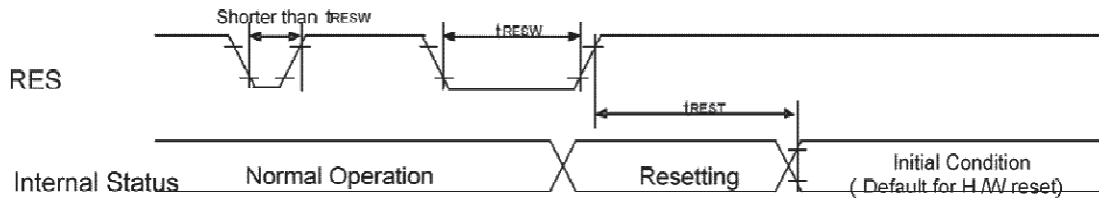
**Serial Interface Characteristics**
**4-Wire SPI Serial Interface Characteristics**


Signal	Symbol	Parameter	MIN	MAX	Unit	Description
SCL	T <sub>SCYC</sub>	Clock cycle (Write)	20		ns	-
	T <sub>SCYC</sub>	Clock cycle (Read)	300		ns	
	T <sub>SCH</sub>	Clock "H" pulse width (Write)	9		ns	
	T <sub>SCH</sub>	Clock "H" pulse width (Read)	140		ns	
	T <sub>SCL</sub>	Clock "L" pulse width (Write)	9		ns	
	T <sub>SCL</sub>	Clock "L" pulse width (Read)	140		ns	
	T <sub>SCr</sub>	Clock rise time		2	ns	
	T <sub>SCf</sub>	Clock fall time		2	ns	
CSX	T <sub>CSU</sub>	Chip select setup time	10		ns	-
	T <sub>CH</sub>	Chip select hold time	10		ns	
SDI (SDA)	T <sub>SISU</sub>	Data input setup time	5		ns	-
	T <sub>SIH</sub>	Data input hold time	5		ns	
SDO (SDA)	T <sub>SOD</sub>	Data output setup time		120	ns	-
	T <sub>SOH</sub>	Data output hold time	5		ns	

Note: Logic high and low levels are specified as 20% and 80% of VDDIO for Input signals. Note: Ta = -30 to 70 °C, VDDIO=1.65V to 3.3V, VCI=2.7V to 3.6V, GND=0V

## 2. Display RESET Timing Characteristics

### Reset input timing



### Timing Parameters

Symbol	Parameter	Related Pins	MIN	TYP	MAX	Note	Unit
$t_{RESW}$	*1) Reset low pulse width	RESX	10	-	-	-	$\mu s$
$t_{REST}$	*2) Reset complete time	-	-	-	5	When reset applied during Sleep in mode	ms
		-	-	-	120	When reset applied during Sleep out mode	ms

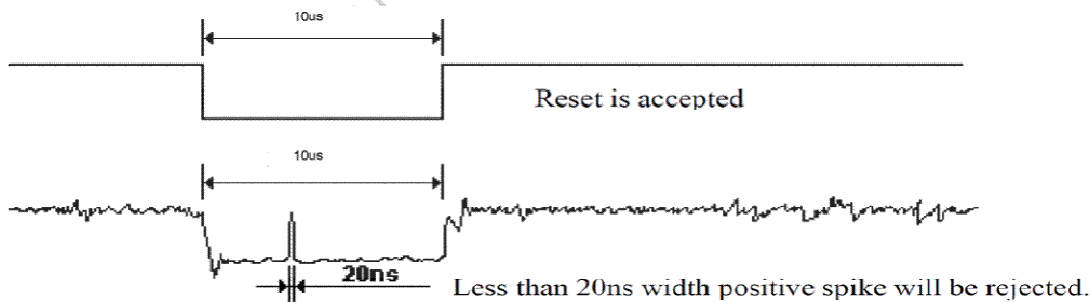
Note 1. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below.

RESX Pulse	Action
Shorter than $5\mu s$	Invalid Reset
Longer than $10\mu s$	Valid Reset
Between $5\mu s$ and $10\mu s$	Reset Initialigation Precedure

Note 2. During the resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode) and then return to Default condition for H/W reset.

Note 3. During Reset Complete Time, data in OTP will be latched to internal register during this period. This loading is done every time when there is H/W reset complete time ( $t_{REST}$ ) within 5ms after a rising edge of RESX.

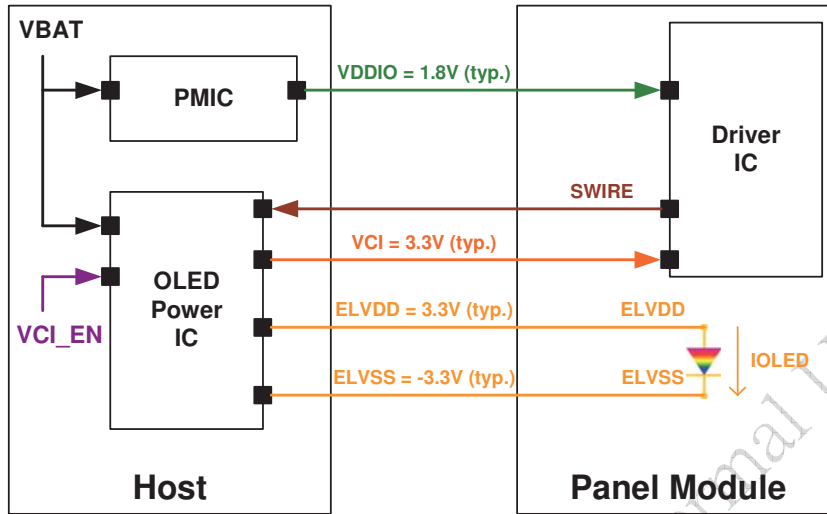
Note 4. Spike Rejection also applies during a valid reset pulse as shown below:



Note 5. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

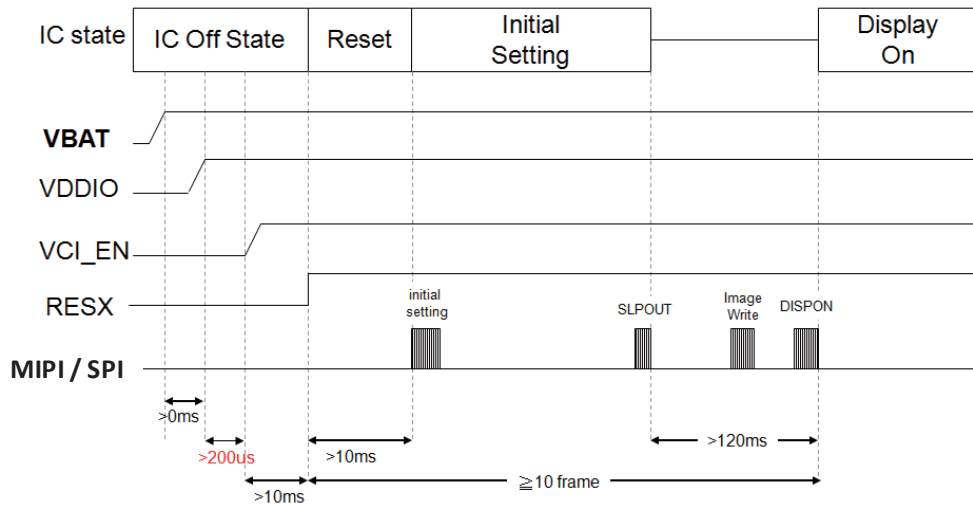
## Operating Sequence

### Power Structure

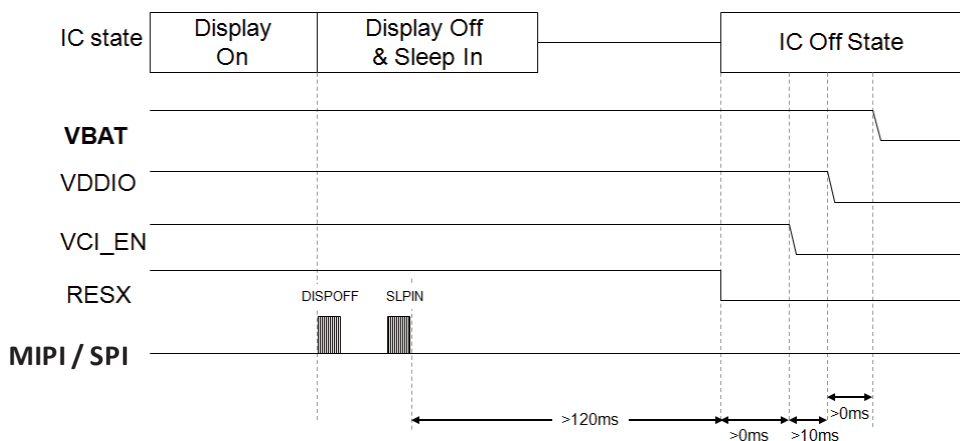


### Display Power on/off Sequence

#### Power on sequence



#### Power off sequence







## E. Optical Specification

Item	Abbr.	Min.	Typ.	Max.	Unit	Remark
Optical Characteristic	Brightness	300	350	--	nits	Note 3
Contrast ratio	@25deg	10000	--	--		Note 4
Brightness Uniformity	350nits	85	--	--		Note 5
Color Temp.	T		7500		K	
Viewing angle CR>1600	Top	80°	--	--	deg	Note 6
	Bottom	80°	--	--	deg	
	Left	80°	--	--	deg	
	Right	80°	--	--	deg	
Color	White	CIE1931 x	0.280	0.300	0.320	Note 7
	White	CIE1931 y	0.290	0.310	0.330	
	Red	CIE1931 x	0.640	0.670	0.700	
	Red	CIE1931 y	0.300	0.330	0.360	
	Green	CIE1931 x	0.186	0.236	0.286	
	Green	CIE1931 y	0.661	0.711	0.761	
	Blue	CIE1931 x	0.090	0.130	0.170	
	Blue	CIE1931 y	0.025	0.065	0.105	
NTSC	CIE x , y	87	100	--	%	
Life time	LT95	25°C	150	--	hrs	Note 8
Flicker		--	--	-30	db	Note 9
Gamma	γ	2.0	2.2	2.4		Note 10
Boost mode	Brightness	--	500	--		Note 11

Note 1: Ambient temperature =25 °C±2 °C, measured by CA-310

Note 2: To be measured in the dark room.

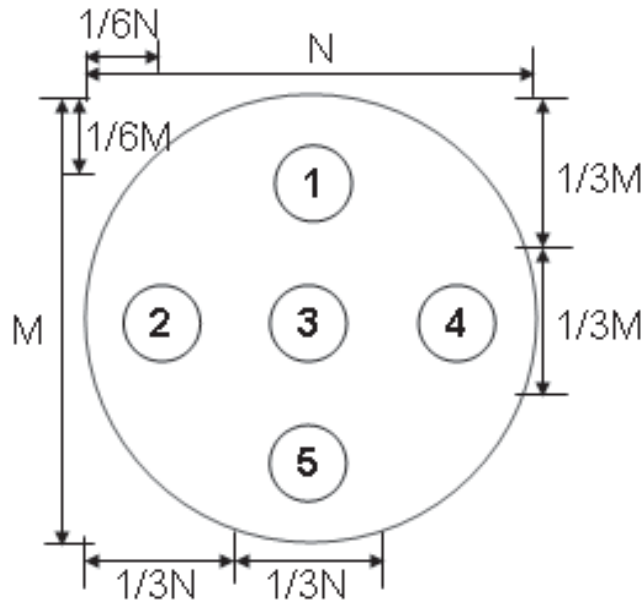
Note 3: The brightness measurement shall be done at the center of the display with a full white image.

Note 4: Definition of contrast ratio:

Contrast ratio is calculated with the following formula:

$$\text{Contrast ratio (CR)} = \frac{\text{Photo detector output when OLED is at "White" state}}{\text{Photo detector output when OLED is at "Black"}}$$

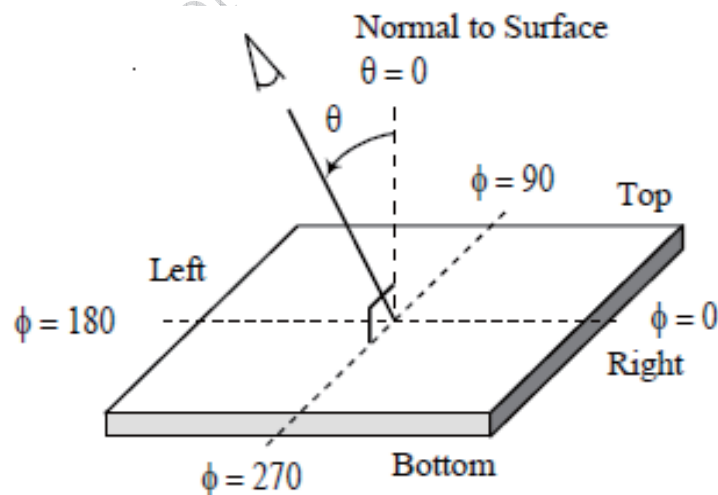
Note 5: Uniformity. Refer to figure as below



- The test condition at  $25^{\circ}\text{C}$  and measured on the surface of display module
- Measurement equipment: CS2000 or similar equipments
- $\Delta B_p = B_p (\text{Min.}) / B_p (\text{Max.}) \times 100 (\%)$
- $B_p (\text{Max.})$  = Maximum brightness in 5 measured spots
- $B_p (\text{Min.})$  = Minimum brightness in 5 measured spots.

Note 6: Definition of viewing angle :

The optical performance is specified as the driver IC located at  $\approx 270^{\circ}$



Note 7: The color chromaticity should be based on sample performance because new OLED material should be verified later.

Note 8: Time to 95% Luminance

To measure the burn-in effect, a test pattern with white background applied to the AMOLED display at 100% loading

Note 9: Flicker

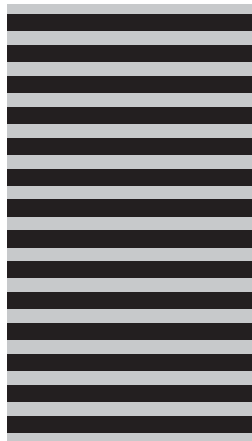
The flicker level is defined using Fast Fourier Transformation (FTT) as follows:

$$Flicker = 20 \log_{10} \left( 2 \frac{f_{FFTC}(n)}{f_{FFTC}(0)} \right) + FS(Hz) \quad (dB)$$

where fFFTC(n) is the nth FFT coefficient, and fFFTC(0) is the 0th FFT coefficient which is DC component. FS(Hz) is the flicker sensitivity as a function of frequency.

The flicker level shall be measured with the test pattern in below.

The gray levels of test pattern is 128.

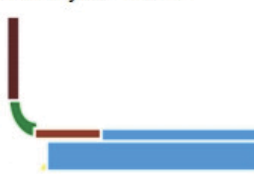


Note 10 : Gamma spec. is based on Gray level 255, 250, 244, 240, 232, 224, 206, 192, 160, 128, 95, 63, 47 & 31.

Note 11 : Boost mode only guarantee the brightness.

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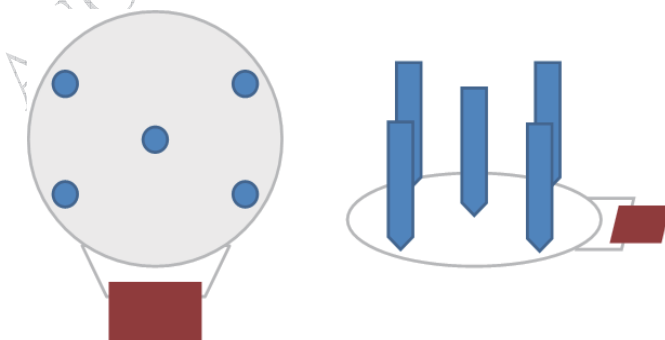
## F. Reliability Test Items

Category	No.	Test items	Conditions	Remark
Reliability (Environment)	1	High Temp. Operation	Ta= 70°C 240 hrs	Reliability (Environment)
	2	High Temp. Storage	Ta= 80 °C 240 hrs	
	3	Low Temp. Operation	Ta= -20 °C 240 hrs	
	4	Low Temp. Storage	Ta= -30 °C 240 hrs	
	5	High Temp./Humi. Operation	Ta= 60 °C. 90% RH 120 hrs	
	6	High Temp./Humi. Storage	Ta= 60 °C. 90% RH 240 hrs	
	7	Thermal Shock	-30 °C ~70 °C, Dwell for 30 min. 100 cycles	Non-operation
RELIABILITY	8	Electrical Static Discharge	Contact: ±4kV, 150pF/330Ω ( power on. Each edge selected one position, a total of 5 position ) Air: ±8kV, 150pF/330Ω ( power on. Each edge selected one position, a total of 5 position )	Note 11
	9	Box Vibration / Drop	Random Vibration : 1 corner, 3 Edges, 6 Surfaces	
	10	FPC Peeling Test	pull stress > 5N /cm speed 50mm/min, 90° , FPC no peel off, Peeling direction: 90°; Velocity:50mm/min.  Pulling upward by 90 °	

Judge Criteria: No functional defect.

Note 11:

ESD position refer to figure as below



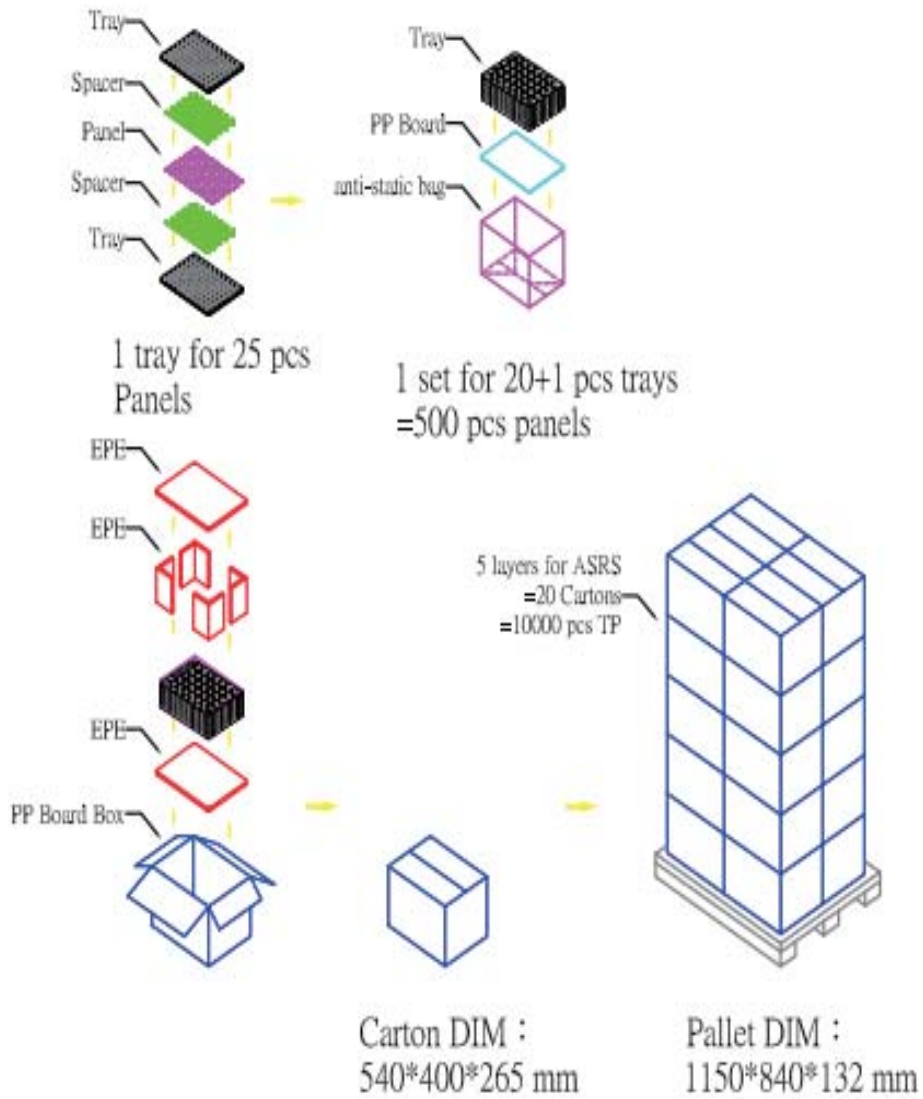
Each panel 5 point, 1 point 5 times

## G. Precautions

Please pay attention to the following items when you use the OLED Modules(Panel):

1. Do not twist or bend the module(panel) and prevent the unsuitable external force for display during assembly.
2. Adopt measures for good heat radiation. Be sure to use the module(panel) within the specified temperature.
3. Avoid dust or oil mist during assembly.
4. Follow the correct power sequence while operating. Do not apply the invalid signal, otherwise, it will cause improper shut down and damage the module(panel).
5. Less EMI: it will be more safety and less noise.
6. Please operate module(panel) in suitable temperature. The response time & brightness will drift by different temperature.
7. Avoid to display the fixed pattern (exclude the white pattern) in a long period, otherwise, it will cause image sticking.
8. Please be sure to turn-off the power when connecting or disconnecting the circuit.
9. Polarizer scratches easily, please handle it carefully.
10. Display surface never likes dirt or stains.
11. A dew drop may lead to destruction. Please wipe off any moisture before using module(panel).
12. Sudden temperature changes cause condensation, and it will cause polarizer damaged.
13. High temperature and humidity may degrade performance. Please do not expose the module(panel) to the direct sunlight and so on.
14. Acetic acid or chlorine compounds are not friends with AMOLED display module(panel).
15. Static electricity will damage the module(panel), please do not touch the module(panel) without any grounded device.
16. Please avoid any static electricity damage (ESD) during producing and operating.
17. Do not disassemble and reassemble the module(panel) by self.
18. Be careful do not touch the rear side directly.
19. No strong vibration or shock. It will cause module(panel) broken.
20. Storage the modules(panel) in suitable environment with regular packing.
21. Be careful of injury from a broken display module(panel).
22. Please avoid the pressure adding to the surface (front or rear side) of modules(panel), because it will cause the display non-uniformity or other function issue.

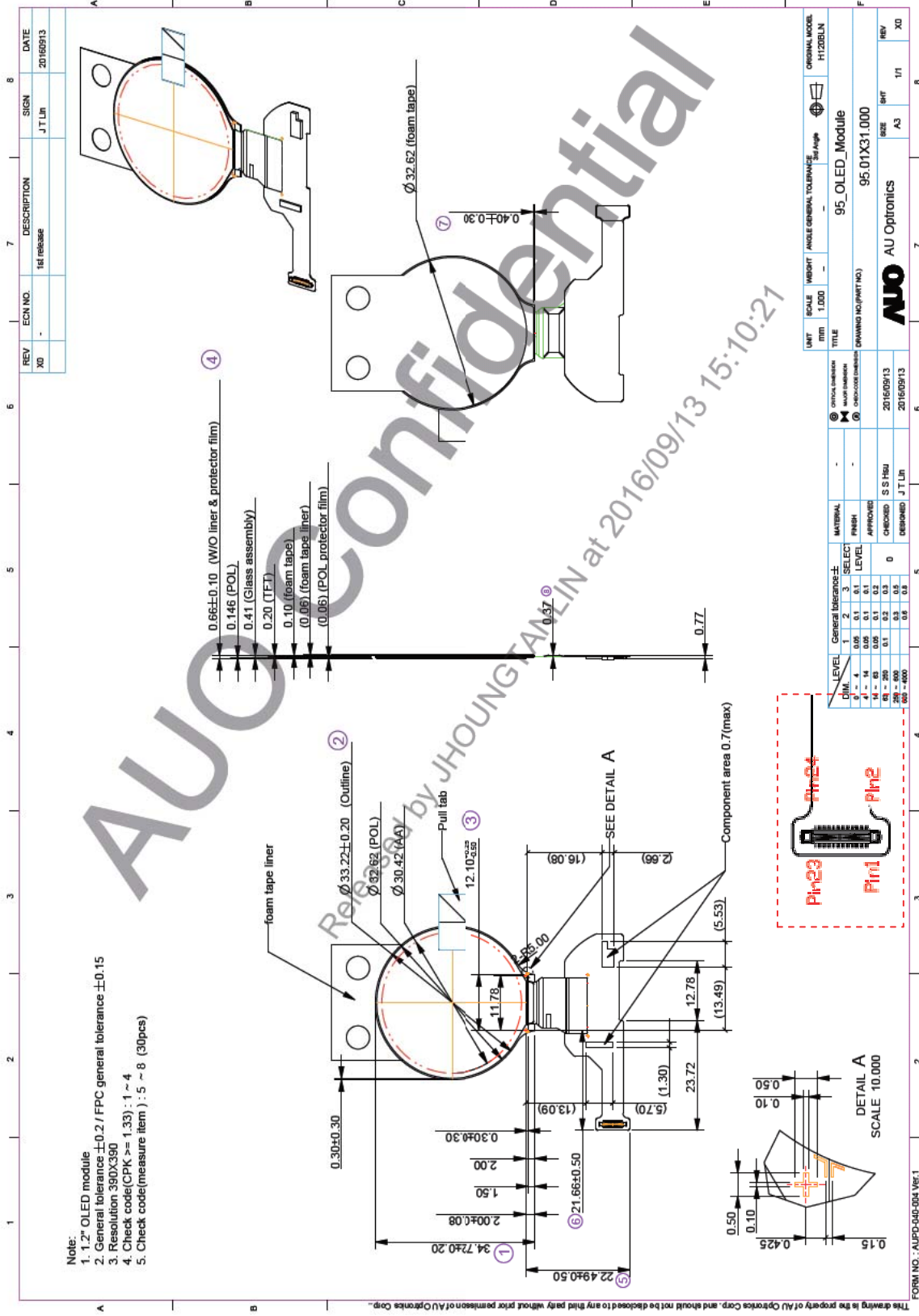
## H. Packing Information



Only

A

# I. Outline Dimension



95.01X31.000\_X120  
BLN01\_95\_drawing\_